Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.050”**

**ANODE**

**.026 x .026”**

**.050”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .026 x .026”**

**Backside Potential: CATHODE**

**Mask Ref: CPD22**

**APPROVED BY: DK DIE SIZE .050” X .050” DATE: 1/16/23**

**MFG: CENTRAL SEMI THICKNESS .010” P/N: 1N5622**

**DG 10.1.2**

#### Rev B, 7/1